

EXHIBIT B

Response to "1st batch of Qualification Lots"

Page 1 of 5

Response Clemens Quinones/Cebu/Fairchild 06/07 04:09 PM	Subject:	>Look Ahead Qualification Assembly Results
	Response to:	1st batch of Qualification Lots
	Category:	Wireless SO-8 Pkg Dev't (FLIP-CLIP Technology, Matrix Mold Thru Gate Design)
	Keywords:	Wireless SO-8 Matrix Package Development

Submitted by: Cristina Estacio

▼ SDI Communication on Dimension problem

Ma Cristina B Estacio 06/07 04:23 AM

To: patrick@sharpmax.com.hk, Mina Alvarez <mina@pdii.com>
 cc: Clemens Quinones/Cebu/Fairchild@Fairchild (bcc: Ma Cristina B Estacio/Cebu/Fairchild)
 Subject: URGENT: SDI to Correct as per drawing

Hi Patrick,

We have made some actual crosssections on the units and the actual parts do not meet as per dimensional requirement. Pls discuss this with your Engg guys so we can correct on the 200K order. Pls confirm ASAP.

Attached is the build diagram of the frame design with the die. These are the dimensional comparison made:

Drawing req't: Actual measurement:

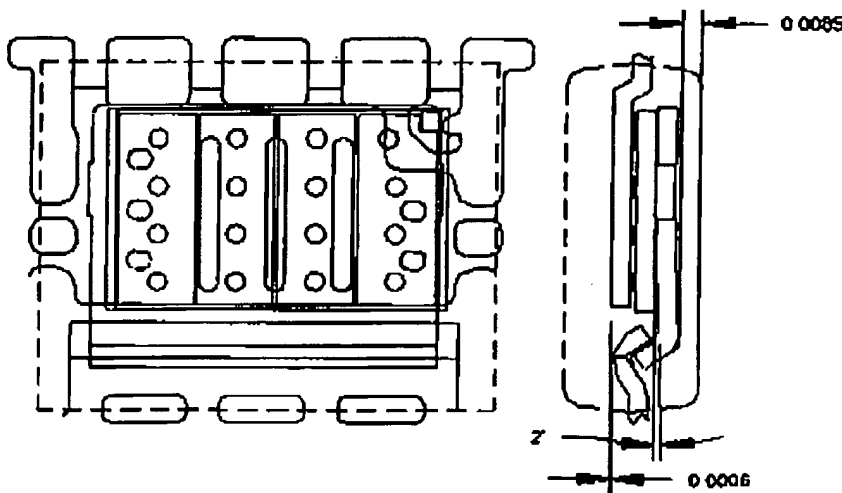
Clip angle 2 degrees 5 - 6 degrees

Level difference 0.6 mil 2.6 - 2.8 mils

bet. v-groove and pad.



SDI_concern.xls



Response to "1st batch of Qualification Lots"

Page 2 of 5

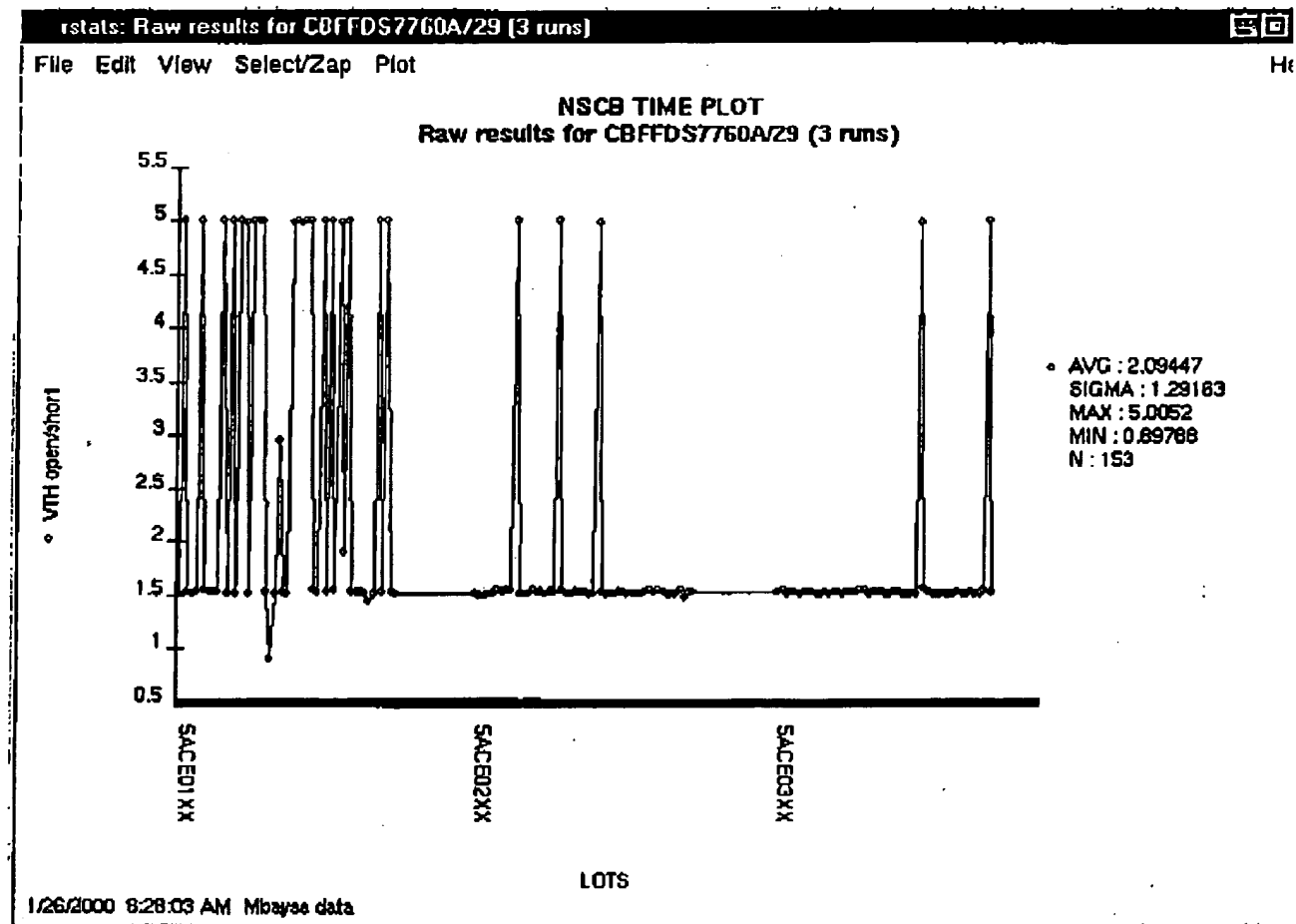
If we meet dimensions as per dwg, clearance from the clip to the mold pkg is 8.5 mils, currently this is very small as per actual cross-sections.

► Rey D Maligro

▼ Vth Plot on O/S Failures

To: Rey D Maligro/Cebu/Fairchild@Fairchild, Darwin C Linao/Cebu/Fairchild@Fairchild
cc:
Subject:

Below is the Vth plot for the open and short parameters. Data showed fallouts to be open with readings reaching compliance of 5V for all the lots. Lot 1 exhibited gross open failures while the rest are minimal.



▼ Planarity measurement on die back after reflow

To: Ma Cristina B Estacio/Cebu/Fairchild@Fairchild
cc:
Subject: Re: Update on the builds

Hi Cristina,
for the first lot i am sending att. to you mesuring result.

Response to "1st batch of Qualification Lots"

Page 3 of 5

we have build 7 LF and placed 840 chips.
(See attached file: Fairchild lot1.xls)
brgd chb



- Fairchild lot1.xls

▼ Email Communication to Alphasem Vendor Re Solder Dispensing @ ClipBonding

From: Ma Cristina B Estacio on [REDACTED] 02:10 PM ZE8
To: meler.p@alphasem.com, schudel.d@alphasem.com, schwarz.m@alphasem.com, fehr.t@alphasem.com
cc: Vincent B Sanil/Cebu/Fairchild@Fairchild, Clemens Quinones/Cebu/Fairchild@Fairchild (bcc: Ma Cristina B Estacio/Cebu/Fairchild)
Subject: Re: Update on the builds

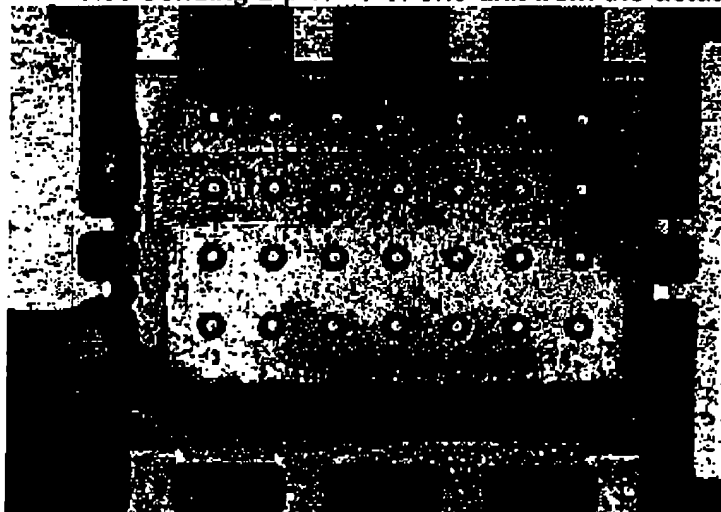
Hi Daniel/Oliver/Markus/ Peter,

We have inspected the actual units and more or less the attached drawing represents how the units look like (actual measurements can only be available after we can sample some units for crosssection.) The concern is on the amount of paste dispensed on the die backside during clip attach. This was highlighted during the sample builds that we have done when I was there but since we did not have the luxury to further optimize the amount of paste dispensed both on the die back and v-groove, the suggestion based on the informal discussions that we had was to redesign the dispense tool. Pls confirm if the dispense tool with the optimum design will be available upon shipment of the clipbender.



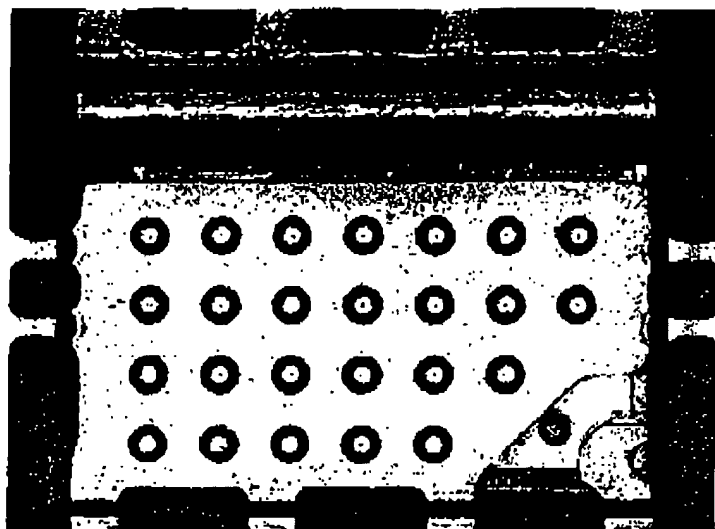
Fairchild Clip SOIC8_elph.dwg

I am also sending a picture of one unit from the actual build.



Response to "1st batch of Qualification Lots"

Page 4 of 5

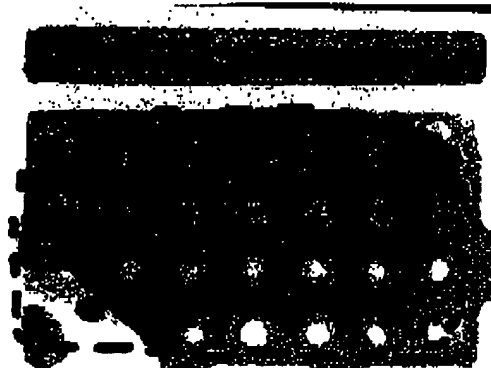
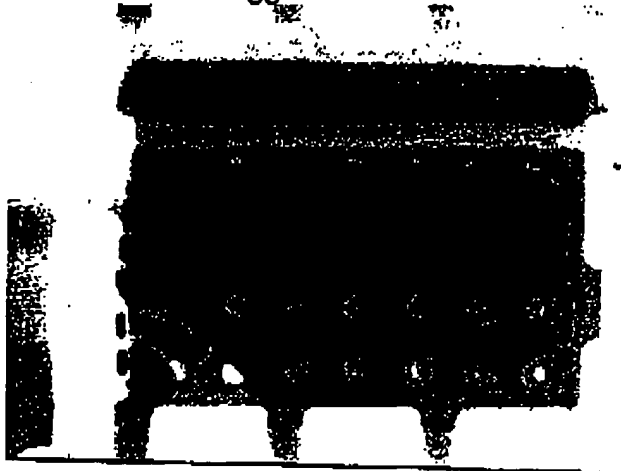


flipclip.jpg topframe.jpg

From: Ma Cristina B Estacio on 8/17/2003 03:31 PM ZE8

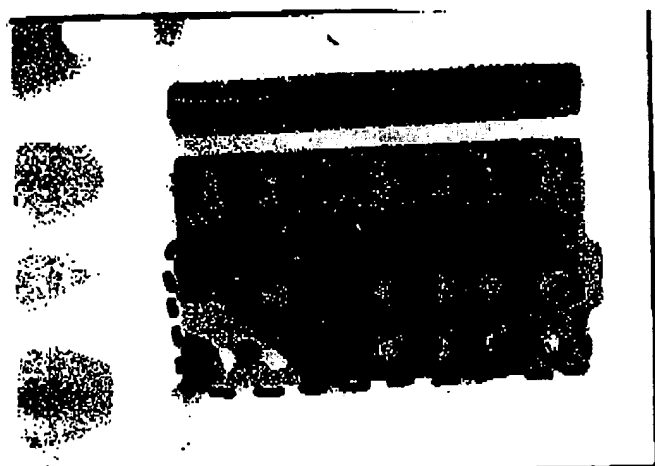
To: meier.p@alphasem.com, schudel.d@alphasem.com, schwarz.m@alphasem.com, fehr.t@alphasem.com
cc: Vincent B Sanil/Cebu/Fairchild@Fairchild, Clemens Quinones/Cebu/Fairchild@Fairchild (bcc: Ma Cristina B Estacio/Cebu/Fairchild)
Subject: Re: Update on the builds

Further to the inputs that I have sent awhile ago, attached are the x-ray pictures which showed voids due to the gap between the die back and drain clip near the v-groove area. Thus the need to definitely have the optimize dispense tool design for the drain clip attach in time when the clipbonder arrives in FSC. (Note: The red bold dotted lines are the wetted portion of the die backside to the drain clip based on our interpretation on the x-ray results). Need your comments and suggestions. Thanks.



Response to "1st batch of Qualification Lots"

Page 5 of 5



voids_xray1.jpg voids_xray2.jpg voids_xray3.jpg

Document Modification Log*

[All Documents](#) [By Author](#) [By Category](#) [By Alternate Name](#) [Go Back](#)